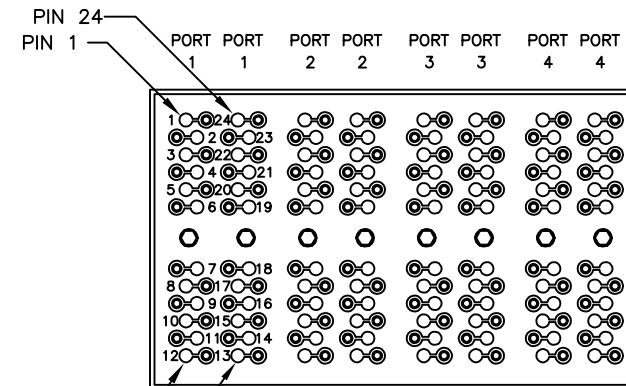
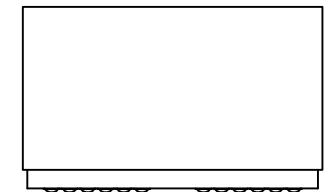
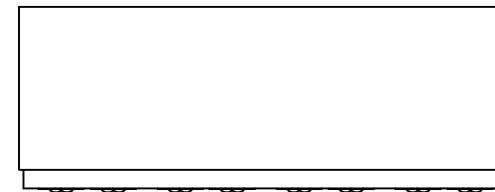
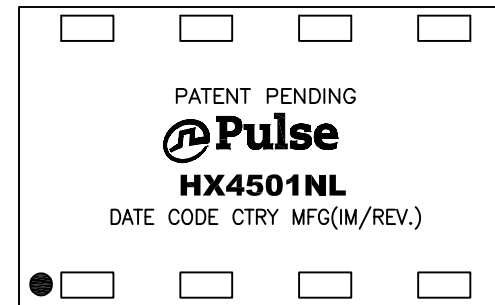




NOTES:

1. ROHS COMPLIANT
2. HEADER: THERMOSET PLASTIC MATERIAL WITH FLAMMABILITY RATING UL 94V-0 OR BETTER.
3. STORAGE TEMPERATURE: -50°C TO +125°C
4. COMPLIANCE TO J-STD:
 - A. J-STD-002: SOLDERABILITY AT 245°C REFLOW PROFILE
 - B. J-STD-020: LEVEL 1, NO MOISTURE SENSITIVE
 - C. J-STD-075: R4, 260°C MAXIMUM THROUGH REFLOW SOLDER
5. TO ORDER TAPE & REEL PACKAGING ADD A "T" SUFFIX TO THE PART NUMBER(i.e HX4501NL BECOMES HX4501NLT).



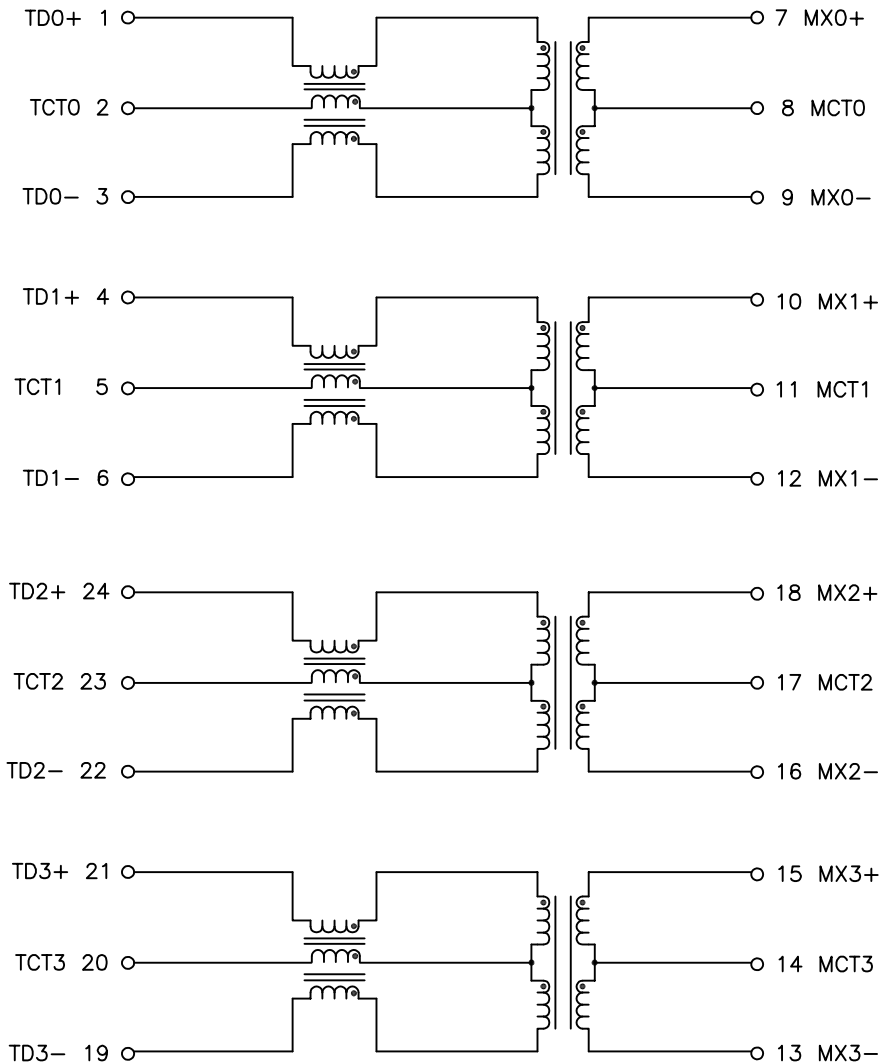
PIN 12

PIN 13

FINAL OUTLINE

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PRODUCT DESCRIPTION	TLA DRAWING	PS DRAWING	SHEET	PART NO.	DATASHEET REV.
MDL,SIN,2.5GD,1:1,SM,TU	HX4501NL-X1	PS-2435.001-D	1 OF 3	HX4501NL	A



SCHEMATIC

ELECTRICAL CHARACTERISTICS AT +25°C UNLESS OTHER SPECIFIED
MEETS IEEE 802.3 SPECIFICATION

PARAMETER	SPECIFICATIONS	
OPERATING TEMPERATURE	-40°C TO +85°C	
URNS RATIO	1.00 ± 2%	
POLARITY	PER SCHEMATIC	
INSERTION LOSS (SDD21&SDD12)	1-50 MHz	50-125 MHz
	-0.5 dB MAX	-1.0 dB MAX
PHY-SIDE RETURN LOSS (SDD11 - Zref = 100 OHMS ± 1%)	1 MHz-40 MHz	40 MHz-200 MHz
	-20 dB MIN	-20+15*LOG ₁₀ (f/40) dB MIN
LINE-SIDE RETURN LOSS (SDD22 - Zref = 100 OHMS ± 1%)	1 MHz-40 MHz	40 MHz-200 MHz
	-20 dB MIN	-20+15*LOG ₁₀ (f/40) dB MIN
INDUCTANCE (OCL)	180 uH MIN @ 100 kHz, 100 mV	
CROSSTALK, ADJACENT CHANNELS (SDD21 - ADJ.)	1-125 MHz	
	-30 dB MIN	
COMMON MODE REJECTION RATIO (SCC21)	30 MHz-200 MHz	
	-30 dB MIN	
COMM. TO DIFF. REJECTION RATIO (SDC12)	10 MHz-125 MHz	
	-45+f/35 dB MIN	
INPUT - OUTPUT ISOLATION	1500 VRMS MIN @ 60 SECONDS	

NOTE: f IS FREQUENCY IN MHZ.

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PRODUCT DESCRIPTION	TLA DRAWING	PS DRAWING	SHEET	PART NO.	DATASHEET REV.
MDL,SIN,2.5GD,1:1,SM,TU	HX4501NL-X1	PS-2435.001-D	2 OF 3	HX4501NL	A